

# ESP8684-WROOM-02C

# ESP8684-WROOM-02UC

Datasheet Version 1.3

2.4 GHz Wi-Fi (802.11 b/g/n) and Bluetooth® 5 module

Built around ESP8684 series of SoC, RISC-V single-core microprocessor

2 MB/4 MB flash in chip package

14 GPIOs

On-board PCB antenna or external antenna connector



ESP8684-WROOM-02C



ESP8684-WROOM-02UC



# 1 Module Overview

**Note:**

Check the link or the QR code to make sure that you use the latest version of this document:  
[https://www.espressif.com/sites/default/files/documentation/esp8684-wroom-02c\\_datasheet\\_en.pdf](https://www.espressif.com/sites/default/files/documentation/esp8684-wroom-02c_datasheet_en.pdf)



## 1.1 Features

### CPU and On-Chip Memory

- ESP8684H2X or ESP8684H4X embedded, 32-bit RISC-V single-core processor, up to 120 MHz
- 576 KB ROM
- 272 KB SRAM (16 KB for cache)
- In-Package flash (see details in Table 1 and Table 2)
- Access to flash accelerated by cache
- Supports flash In-Circuit Programming (ICP)

### Wi-Fi

- 802.11 b/g/n
- Center frequency range of operating channel: 2412 ~ 2484 MHz
- Supports 20 MHz bandwidth in 2.4 GHz band
- 1T1R mode with data rate up to 72.2 Mbps
- Wi-Fi Multimedia (WMM)
- TX/RX A-MPDU, TX/RX A-MSDU
- Immediate Block ACK
- Fragmentation and defragmentation
- Transmit opportunity (TXOP)
- Automatic Beacon monitoring (hardware TSF)
- 3 × virtual Wi-Fi interfaces
- Simultaneous support for Infrastructure BSS in Station mode, SoftAP mode, Station + SoftAP mode, and promiscuous mode

*Note that when ESP8684 series scans in Station mode, the SoftAP channel will change along with the Station channel*

### Bluetooth®

- Bluetooth LE: Bluetooth 5.3 certified
- High power mode (20 dBm)
- Speed: 125 kbps, 500 kbps, 1 Mbps, 2 Mbps
- Advertising extensions
- Multiple advertisement sets
- Channel selection algorithm #2
- Internal co-existence mechanism between Wi-Fi and Bluetooth to share the same antenna

### Peripherals

- Up to 14 GPIOs
  - 2 strapping GPIOs
- GPIO, SPI, UART, I2C, LED PWM controller, general DMA controller, SAR ADC, temperature sensor, general-purpose timers, system timers, and watchdog timers

**Note:**

\* Please refer to [ESP8684 Series Datasheet](#) for detailed information about the module peripherals.

### Integrated Components on Module

- 26 MHz crystal oscillator

## Antenna Options

- On-board PCB antenna (ESP8684-WROOM-02C)
- External antenna via a connector (ESP8684-WROOM-02UC)

- Operating ambient temperature:  $-40 \sim 105 \text{ }^{\circ}\text{C}$

## Certification

- RF certification: See [certificates](#)
- Green certification: RoHS/REACH

## Operating Conditions

- Operating voltage/Power supply:  $3.0 \sim 3.6 \text{ V}$

## Test

- HTOL/HTSL/uHAST/TCT/ESD/Latch-up

## 1.2 Series Comparison

ESP8684-WROOM-02C and ESP8684-WROOM-02UC are two generic Wi-Fi and Bluetooth LE modules. The rich set of peripherals and high performance make the modules an ideal choice for smart homes, industrial automation, health care, consumer electronics, etc.

ESP8684-WROOM-02C comes with an on-board PCB antenna. ESP8684-WROOM-02UC comes with a connector for an external antenna. Both ESP8684-WROOM-02C and ESP8684-WROOM-02UC are available in two variants that integrate the ESP8684H2X and ESP8684H4X chip respectively.

The series comparison for the two modules is as follows:

**Table 1: ESP8684-WROOM-02C (ANT) Series Comparison<sup>1</sup>**

Ordering Code	In-Package flash <sup>2,3</sup>	Chip Revision <sup>4</sup>	Ambient Temp. <sup>5</sup> ( $^{\circ}\text{C}$ )	Size <sup>6</sup> (mm)
ESP8684-WROOM-02C-H2X	2 MB	v2.0	$-40 \sim 105$	$18.0 \times 20.0 \times 3.2$
ESP8684-WROOM-02C-H4X	4 MB			

<sup>1</sup> This table shares the same notes presented in Table 2 below.

**Table 2: ESP8684-WROOM-02UC (CONN) Series Comparison**

Ordering Code	In-Package flash <sup>2,3</sup>	Chip Revision <sup>4</sup>	Ambient Temp. <sup>5</sup> ( $^{\circ}\text{C}$ )	Size <sup>6</sup> (mm)
ESP8684-WROOM-02UC-H2X	2 MB	v2.0	$-40 \sim 105$	$18.0 \times 14.3 \times 3.2$
ESP8684-WROOM-02UC-H4X	4 MB			

<sup>2</sup> The in-package flash supports:

- More than 100,000 program/erase cycles
- More than 20 years data retention time

<sup>3</sup> By default, the SPI flash on the module operates at a maximum clock frequency of 60 MHz and does not support the auto suspend feature. If you need the flash auto suspend feature, please [contact us](#).

<sup>4</sup> Compared to previous chip versions, chip version v2.0 provides an additional 20 KB of SRAM and approximately 100 KB of flash memory (subject to actual application).

<sup>5</sup> Ambient temperature specifies the recommended temperature range of the environment immediately outside the Espressif module.

<sup>6</sup> For details, refer to Section [10.1 Module Dimensions](#).

The ESP8684H2X chip and the ESP8684H4X chip fall into the same category, namely ESP8684 chip series. ESP8684 series of chips have a 32-bit RISC-V single-core processor.

They integrate a rich set of peripherals including GPIO, SPI, UART, I2C, LED PWM controller, general DMA controller, SAR ADC, temperature sensor, general-purpose timers, system timers, and watchdog timers.

**Note:**

For more information on ESP8684, please refer to [ESP8684 Series Datasheet](#).

## 1.3 Applications

- Smart Home
- Industrial Automation
- Health Care
- Consumer Electronics
- Smart Agriculture
- POS Machines
- Service Robot
- Generic Low-power IoT Sensor Hubs
- Generic Low-power IoT Data Loggers

# Contents

<b>1</b>	<b>Module Overview</b>	<b>2</b>
1.1	Features	2
1.2	Series Comparison	3
1.3	Applications	4
<b>2</b>	<b>Block Diagram</b>	<b>9</b>
<b>3</b>	<b>Pin Definitions</b>	<b>10</b>
3.1	Pin Layout	10
3.2	Pin Description	10
<b>4</b>	<b>Boot Configurations</b>	<b>12</b>
4.1	Chip Boot Mode Control	13
4.2	ROM Messages Printing Control	13
<b>5</b>	<b>Peripherals</b>	<b>15</b>
5.1	Peripheral Overview	15
5.2	Peripheral Description	15
5.2.1	Connectivity Interface	15
5.2.1.1	UART Controller	15
5.2.1.2	SPI Controller	16
5.2.1.3	I2C Controller	17
5.2.1.4	LED PWM Controller	17
5.2.2	Analog Signal Processing	17
5.2.2.1	SAR ADC	18
5.2.2.2	Temperature Sensor	18
<b>6</b>	<b>Electrical Characteristics</b>	<b>19</b>
6.1	Absolute Maximum Ratings	19
6.2	Recommended Operating Conditions	19
6.3	DC Characteristics (3.3 V, 25 °C)	19
6.4	Current Consumption Characteristics	20
6.4.1	Current Consumption in Active Mode	20
6.4.2	Current Consumption in Other Modes	20
<b>7</b>	<b>RF Characteristics</b>	<b>22</b>
7.1	Wi-Fi Radio	22
7.1.1	Wi-Fi RF Standards	22
7.1.2	Wi-Fi RF Transmitter (TX) Characteristics	22
7.1.3	Wi-Fi RF Receiver (RX) Characteristics	23
7.2	Bluetooth LE Radio	24
7.2.1	Bluetooth LE RF Transmitter (TX) Characteristics	24
7.2.2	Bluetooth LE RF Receiver (RX) Characteristics	25

<b>8</b>	<b>Module Schematics</b>	28
<b>9</b>	<b>Peripheral Schematics</b>	30
<b>10</b>	<b>Physical Dimensions</b>	31
10.1	Module Dimensions	31
10.2	Dimensions of External Antenna Connector	32
<b>11</b>	<b>PCB Layout Recommendations</b>	33
11.1	PCB Land Pattern	33
11.2	Module Placement for PCB Design	34
<b>12</b>	<b>Product Handling</b>	35
12.1	Storage Conditions	35
12.2	Electrostatic Discharge (ESD)	35
12.3	Reflow Profile	35
12.4	Ultrasonic Vibration	36
	<b>Related Documentation and Resources</b>	37
	<b>Revision History</b>	38

## List of Tables

1	ESP8684-WROOM-02C (ANT) Series Comparison <sup>1</sup>	3
2	ESP8684-WROOM-02UC (CONN) Series Comparison	3
3	Pin Definitions	11
4	Default Configuration of Strapping Pins	12
5	Description of Timing Parameters for the Strapping Pins	12
6	Chip Boot Mode Control	13
7	UART0 ROM Message Printing Control	14
8	Absolute Maximum Ratings	19
9	Recommended Operating Conditions	19
10	DC Characteristics (3.3 V, 25 °C)	19
11	Current Consumption Depending on RF Modes	20
12	Current Consumption in Modem-sleep Mode	20
13	Current Consumption in Low-Power Modes	20
14	Wi-Fi RF Standards	22
15	TX Power with Spectral Mask and EVM Meeting 802.11 Standards	22
16	TX EVM Test	23
17	RX Sensitivity	23
18	Maximum RX Level	23
19	RX Adjacent Channel Rejection	24
20	Transmitter General Characteristics	24
21	Transmitter Characteristics - Bluetooth LE 1 Mbps	24
22	Transmitter Characteristics - Bluetooth LE 2 Mbps	25
23	Transmitter Characteristics - Bluetooth LE 125 kbps	25
24	Transmitter Characteristics - Bluetooth LE 500 kbps	25
25	Receiver Characteristics - Bluetooth LE 1 Mbps	26
26	Receiver Characteristics - Bluetooth LE 2 Mbps	26
27	Receiver Characteristics - Bluetooth LE 125 kbps	27
28	Receiver Characteristics - Bluetooth LE 500 kbps	27

## List of Figures

1	ESP8684-WROOM-02C Block Diagram	9
2	ESP8684-WROOM-02UC Block Diagram	9
3	Pin Layout (Top View)	10
4	Visualization of Timing Parameters for the Strapping Pins	13
5	ESP8684-WROOM-02C Schematics	28
6	ESP8684-WROOM-02UC Schematics	29
7	Peripheral Schematics	30
8	ESP8684-WROOM-02C Physical Dimensions	31
9	ESP8684-WROOM-02UC Physical Dimensions	31
10	Dimensions of External Antenna Connector	32
11	ESP8684-WROOM-02C Recommended PCB Land Pattern	33
12	ESP8684-WROOM-02UC Recommended PCB Land Pattern	34
13	Reflow Profile	35



## 2 Block Diagram

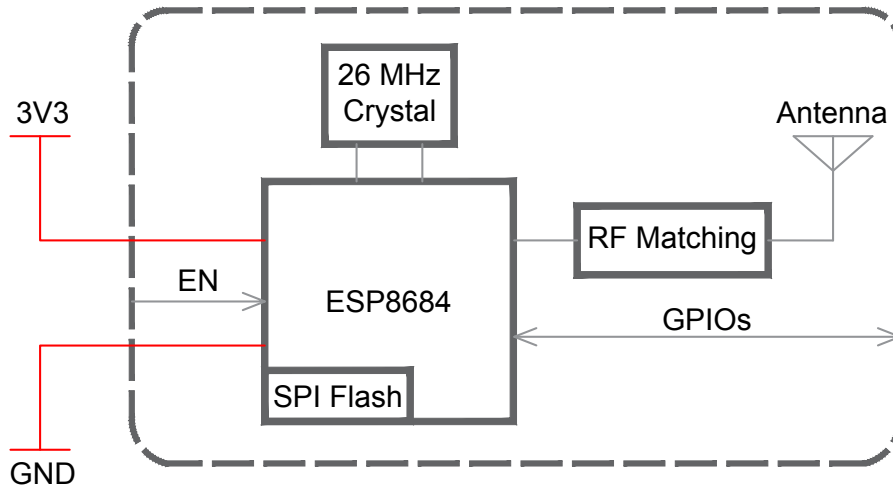


Figure 1: ESP8684-WROOM-02C Block Diagram

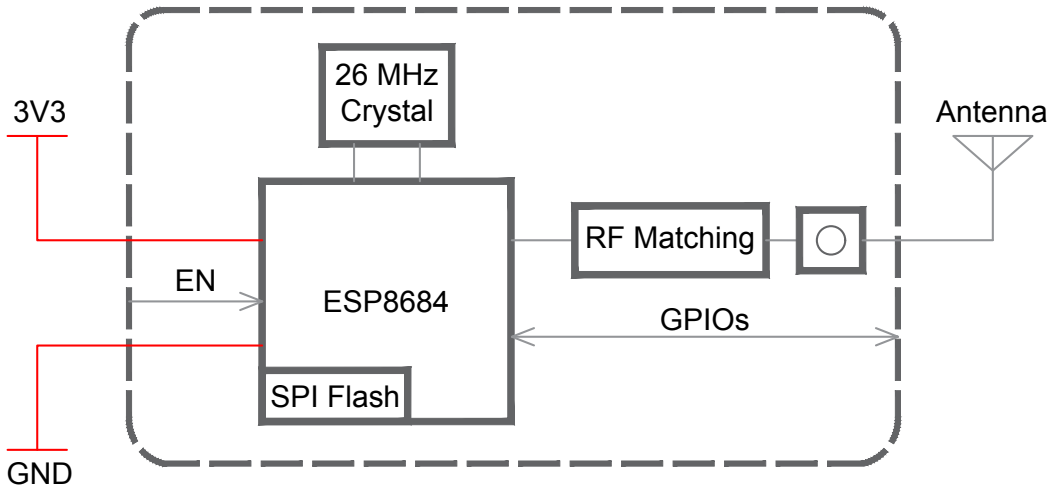


Figure 2: ESP8684-WROOM-02UC Block Diagram

## 3 Pin Definitions

### 3.1 Pin Layout

The pin diagram below shows the approximate location of pins on the module. For the actual diagram drawn to scale, please refer to Figure 10.1 *Module Dimensions*.

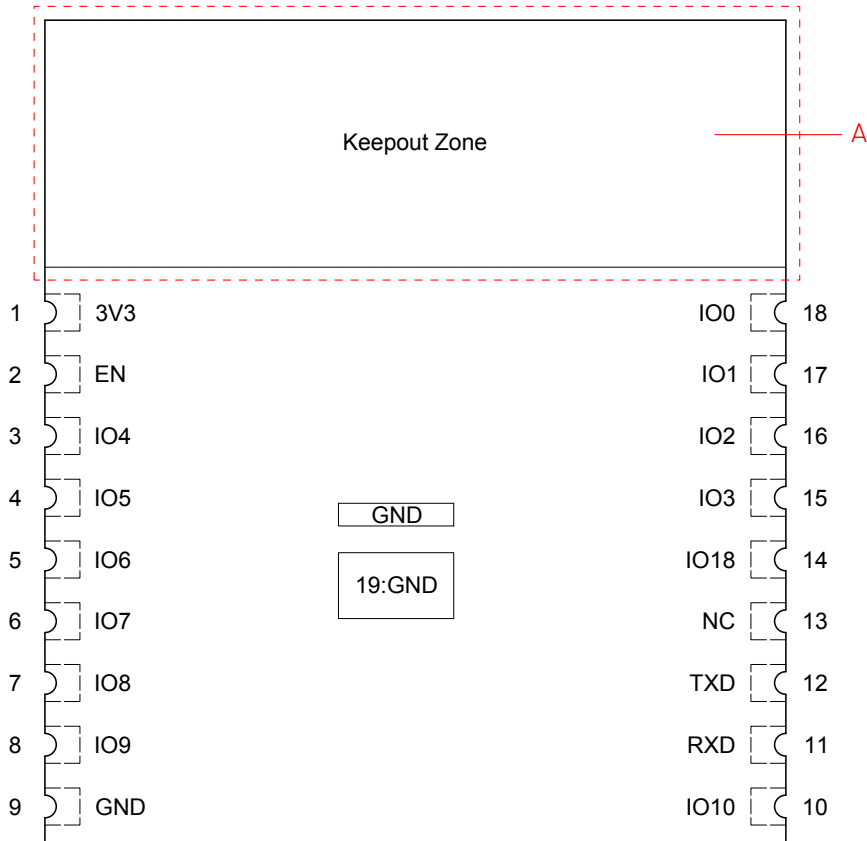


Figure 3: Pin Layout (Top View)

**Note A:**

The zone marked with dotted lines is the antenna keepout zone. The pin diagram is applicable to ESP8684-WROOM-02C and ESP8684-WROOM-02UC, but the latter has no antenna keepout zone.

To learn more about the keepout zone for module's antenna on the base board, please refer to [ESP8684 Hardware Design Guidelines](#) > Section *Positioning a Module on a Base Board*.

### 3.2 Pin Description

ESP8684-WROOM-02UC and ESP8684-WROOM-02C both have 19 pins, respectively. See pin definitions in Table 3 *Pin Description*.

For peripheral pin configurations, please refer to 5.2 *Peripheral Description*.

Table 3: Pin Definitions

Name	No.	Type <sup>1</sup>	Function
3V3	1	P	Power supply
EN	2	I	High: on, enables the chip. Low: off, the chip powers off. Note: Do not leave the CHIP_EN pin floating.
IO4	3	I/O/T	GPIO4, ADC1_CH4, FSPIHD, MTMS
IO5	4	I/O/T	GPIO5, FSPIWP, MTDI
IO6	5	I/O/T	GPIO6, FSPICLK, MTCK
IO7	6	I/O/T	GPIO7, FSPID, MTDO
IO8	7	I/O/T	GPIO8 This pin is internally pulled high.
IO9	8	I/O/T	GPIO9
GND	9	P	Ground
IO10	10	I/O/T	GPIO10, FSPICSO
RXD	11	I/O/T	GPIO19, UORXD
TXD	12	I/O/T	GPIO20, UOTXD
NC	13	—	NC
IO18	14	I/O/T	GPIO18
IO3	15	I/O/T	GPIO3, ADC1_CH3
IO2	16	I/O/T	GPIO2, ADC1_CH2, FSPIQ
IO1	17	I/O/T	GPIO1, ADC1_CH1
IO0	18	I/O/T	GPIO0, ADC1_CH0
GND	19	P	Ground

<sup>1</sup> P: power supply; I: input; O: output; T: high impedance.

**Note:**

IO0, IO1, IO3, IO5/MTDI pins have low-level glitches during chip power up. See details in section General Purpose Input / Output Interface (GPIO) of [ESP8684 Series Datasheet](#).

## 4 Boot Configurations

**Note:**

The content below is excerpted from [ESP8684 Series Datasheet](#) > Section *Boot Configurations*. For the strapping pin mapping between the chip and modules, please refer to Chapter [8 Module Schematics](#).

The module allows for configuring the following boot parameters through strapping pins and eFuse parameters at power-up or a hardware reset, without microcontroller interaction.

- **Chip boot mode**
  - Strapping pin: GPIO8 and GPIO9
- **ROM message printing**
  - Strapping pin: GPIO8
  - eFuse parameter: EFUSE\_UART\_PRINT\_CONTROL

The default values of all the above eFuse parameters are 0, which means that they are not burnt. Given that eFuse is one-time programmable, once programmed to 1, it can never be reverted to 0. For how to program eFuse parameters, please refer to [ESP8684 Technical Reference Manual](#) > Chapter *eFuse Controller*.

The default values of the strapping pins, namely the logic levels, are determined by pins' internal weak pull-up/pull-down resistors at reset if the pins are not connected to any circuit, or connected to an external high-impedance circuit.

**Table 4: Default Configuration of Strapping Pins**

Strapping Pin	Default Configuration	Bit Value
GPIO8	N/A	-
GPIO9	Internal weak pull-up	1

To change the bit values, the strapping pins should be connected to external pull-down/pull-up resistances. If the ESP8684 is used as a device by a host MCU, the strapping pin voltage levels can also be controlled by the host MCU.

All strapping pins have latches. At system reset, the latches sample the bit values of their respective strapping pins and store them until the chip is powered down or shut down. The states of latches cannot be changed in any other way. It makes the strapping pin values available during the entire chip operation, and the pins are freed up to be used as regular IO pins after reset.

The timing of signals connected to the strapping pins should adhere to the *setup time* and *hold time* specifications in Table 5 and Figure 4.

**Table 5: Description of Timing Parameters for the Strapping Pins**

Parameter	Description	Min (ms)
$t_0$	Setup time before CHIP_EN goes from low to high	0
$t_1$	Hold time after CHIP_EN goes high	3

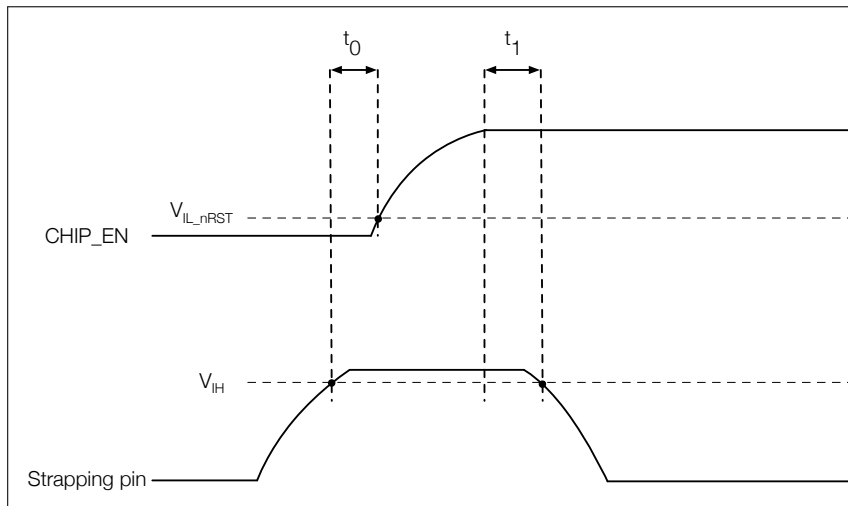


Figure 4: Visualization of Timing Parameters for the Strapping Pins

## 4.1 Chip Boot Mode Control

GPIO8 and GPIO9 control the boot mode after the reset is released. See Table 6 *Chip Boot Mode Control*.

Table 6: Chip Boot Mode Control

Boot Mode	GPIO9	GPIO8
<b>SPI boot mode</b>	<b>1</b>	x <sup>2</sup>
Joint download boot mode <sup>3</sup>	0	1

<sup>1</sup> **Bold** marks the default value and configuration.

<sup>2</sup> Values that have no effect on the result and can therefore be ignored.

<sup>3</sup> Joint Download Boot mode supports UART Download Boot. In addition to SPI Boot and Joint Download Boot modes, ESP8684 also supports SPI Download Boot mode. For details, please see [ESP8684 Technical Reference Manual](#) >

Chapter *Chip Boot Control*.

## 4.2 ROM Messages Printing Control

EFUSE\_UART\_PRINT\_CONTROL and GPIO8 control ROM messages printing to **UART0** as shown in Table 7 *UART0 ROM Message Printing Control*.

Table 7: UART0 ROM Message Printing Control

UART0 ROM Code Printing	eFuse <sup>1</sup>	GPIO8
Enabled	0	Ignored
	1	0
	2	1
Disabled	1	1
	2	0
	3	Ignored

<sup>1</sup> EFUSE\_UART\_PRINT\_CONTROL

## 5 Peripherals

### 5.1 Peripheral Overview

ESP8684 integrates a rich set of peripherals including GPIO, SPI, UART, I2C, LED PWM controller, general DMA controller, SAR ADC, temperature sensor, general-purpose timers, system timers, and watchdog timers.

To learn more about on-chip components, please refer to [ESP8684 Series Datasheet](#) > Section *Functional Description*.

**Note:**

The content below is sourced from [ESP8684 Series Datasheet](#) > Section *Peripherals*. Some information may not be applicable to ESP8684-WROOM-02C and ESP8684-WROOM-02UC as not all the IO signals are exposed on the module.

To learn more about peripheral signals, please refer to [ESP8684 Technical Reference Manual](#) > Section *Peripheral Signal List*.

### 5.2 Peripheral Description

This section describes the chip's peripheral capabilities, covering connectivity interfaces and on-chip sensors that extend its functionality.

#### 5.2.1 Connectivity Interface

This subsection describes the connectivity interfaces on the chip that enable communication and interaction with external devices and networks.

##### 5.2.1.1 UART Controller

The UART Controller in the ESP8684 chip facilitates the transmission and reception of asynchronous serial data between the chip and external UART devices. It supports two UART interfaces.

**Feature List**

- Full-duplex asynchronous communication
- Configurable baud rate, up to 2.5 Mbaud
- Automatic baud rate detection of input signals
- Data frame format:
  - a START bit
  - data bits, ranging from 5 ~ 8
  - a parity bit
  - stop bits, whose length can be 1, 1.5, or 2 bits
- Special character AT\_CMD detection
- Supported protocols: RS485, IrDA

- UART as wake-up source
- Software and hardware flow control
- Three clock sources that can be divided:
  - 40 MHz PLL\_F40M\_CLK
  - internal fast RC oscillator RC\_FAST\_CLK
  - external crystal clock XTAL\_CLK
- 512 x 8-bit RAM shared by TX FIFOs and RX FIFOs of the two UART controllers

### Pin Assignment

For UART, the pins used can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP8684 Series Datasheet](#) > Section *IO Pins* and [ESP8684 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.2 SPI Controller

ESP8684 series features three SPI interfaces (SPI0, SPI1, and SPI2). SPI0 and SPI1 can be configured to operate in SPI memory mode and SPI2 can be configured to operate in general-purpose SPI mode.

SPI0 and SPI1 are reserved for system use, and only SPI2 is available for users.

#### Features of SPI0 and SPI1

- Data is transferred in bytes
- Up to four-line STR reads and writes are supported
- The clock frequency is configurable to a maximum of 60 MHz in STR mode

#### Features of SPI2 General-purpose SPI (GP-SPI)

- It can operate in master and slave modes
- It supports two-line full-duplex communication and single-/two-/four-line half-duplex communication in both master and slave modes
- The host's clock frequency of SPI2 is configurable. The clock frequency is 40 MHz at most
- Data is transferred in bytes
- The clock polarity (CPOL) and phase (CPHA) are also configurable
- The SPI2 interface can connect to GDMA

### Pin Assignment

For SPI2, the pins used can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP8684 Series Datasheet](#) > Section *IO Pins* and [ESP8684 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.



### 5.2.1.3 I2C Controller

The I2C Controller supports communication between the master and slave devices using the I2C bus.

#### Feature List

- one I2C controller operating in master mode
- Standard mode (100 Kbit/s) and fast mode (400 Kbit/s)
- Up to 800 Kbit/s (constrained by SCL and SDA pull-up strength)
- Support for 7-bit and 10-bit addressing, as well as dual address mode
- 7-bit broadcast address

#### Pin Assignment

For I2C, the pins used can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP8684 Series Datasheet](#) > Section *IO Pins* and [ESP8684 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.4 LED PWM Controller

The LED PWM Controller (LEDC) is designed to generate PWM signals for LED control.

#### Feature List

- Six independent PWM generators
- Maximum PWM duty cycle resolution of 14 bits
- Four independent timers with 14-bit counters, configurable fractional clock dividers and counter overflow values
- Adjustable phase of PWM signal output
- PWM duty cycle dithering
- Automatic duty cycle fading
- PWM signal output in low-power mode (Light-sleep mode)

#### Pin Assignment

The pins for the LED PWM Controller can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP8684 Series Datasheet](#) > Section *IO Pins* and [ESP8684 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

## 5.2.2 Analog Signal Processing

This subsection describes components on the chip that sense and process real-world data.

### 5.2.2.1 SAR ADC

ESP8684 integrates a Successive Approximation Analog-to-Digital Converter (SAR ADC) to convert analog signals into digital representations.

#### Feature List

- 12-bit sampling resolution
- Analog voltage sampling from up to five pins
- One DIG ADC controller
  - Provides separate control modules for one-time sampling and multi-channel scanning
  - Supports one-time sampling and multi-channel scanning working simultaneously
  - User-defined scanning sequence in multi-channel scanning mode
  - Provides two filters with configurable filter coefficient
  - Supports threshold monitoring

#### Pin Assignment

The pins for the SAR ADC are multiplexed with GPIO0 ~ GPIO4, JTAG.

For more information about the pin assignment, see [ESP8684 Series Datasheet](#) > Section *IO Pins* and [ESP8684 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.2.2 Temperature Sensor

The Temperature Sensor in the ESP8684 chip allows for real-time monitoring of temperature changes inside the chip.

#### Feature List

- Measurement range:  $-40\text{ }^{\circ}\text{C} \sim 125\text{ }^{\circ}\text{C}$
- Software triggering, wherein the data can be read continuously once triggered
- Configurable temperature offset based on the environment to improve the accuracy
- Adjustable measurement range

## 6 Electrical Characteristics

### 6.1 Absolute Maximum Ratings

Stresses above those listed in Table 8 *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under Table 9 *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Table 8: Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
VDD33	Power supply voltage	-0.3	3.6	V
T <sub>STORE</sub>	Storage temperature	-40	105	°C

### 6.2 Recommended Operating Conditions

Table 9: Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
VDD33	Power supply voltage	3.0	3.3	3.6	V
I <sub>VDD</sub>	Current delivered by external power supply	0.5	—	—	A
T <sub>A</sub>	Operating ambient temperature	-40	—	105	°C

### 6.3 DC Characteristics (3.3 V, 25 °C)

Table 10: DC Characteristics (3.3 V, 25 °C)

Symbol	Parameter	Min	Typ	Max	Unit
C <sub>IN</sub>	Pin capacitance	—	2	—	pF
V <sub>IH</sub>	High-level input voltage	0.75 × VDD <sup>1</sup>	—	VDD <sup>1</sup> + 0.3	V
V <sub>IL</sub>	Low-level input voltage	-0.3	—	0.25 × VDD <sup>1</sup>	V
I <sub>IH</sub>	High-level input current	—	—	50	nA
I <sub>IL</sub>	Low-level input current	—	—	50	nA
V <sub>OH</sub> <sup>2</sup>	High-level output voltage	0.8 × VDD <sup>1</sup>	—	—	V
V <sub>OL</sub> <sup>2</sup>	Low-level output voltage	—	—	0.1 × VDD <sup>1</sup>	V
I <sub>OH</sub>	High-level source current (VDD <sup>1</sup> = 3.3 V, V <sub>OH</sub> ≥ 2.64 V, PAD_DRIVER = 3)	—	40	—	mA
I <sub>OL</sub>	Low-level sink current (VDD <sup>1</sup> = 3.3 V, V <sub>OL</sub> = 0.495 V, PAD_DRIVER = 3)	—	28	—	mA
R <sub>PU</sub>	Pull-up resistor	—	45	—	kΩ
R <sub>PD</sub>	Pull-down resistor	—	45	—	kΩ
V <sub>IH_nRST</sub>	Chip reset release voltage	0.75 × VDD <sup>1</sup>	—	VDD <sup>1</sup> + 0.3	V
V <sub>IL_nRST</sub>	Chip reset voltage	-0.3	—	0.25 × VDD <sup>1</sup>	V

<sup>1</sup> VDD is the I/O voltage for a particular power domain of pins.

<sup>2</sup> V<sub>OH</sub> and V<sub>OL</sub> are measured using high-impedance load.

## 6.4 Current Consumption Characteristics

### 6.4.1 Current Consumption in Active Mode

The current consumption measurements are taken with a 3.3 V supply at 25 °C ambient temperature.

TX current consumption is rated at a 100% duty cycle.

RX current consumption is rated when the peripherals are disabled and the CPU idle.

**Table 11: Current Consumption Depending on RF Modes**

Work mode	Description		Peak (mA)
Active (RF working)	TX	802.11b, 1 Mbps, @21 dBm	310
		802.11g, 54 Mbps, @19 dBm	260
		802.11n, HT20, MCS 7, @18 dBm	250
	RX	802.11b/g/n, HT20	65

**Note:**

The content below is excerpted from *Section Power Consumption in Other Modes* in [ESP8684 Series Datasheet](#).

### 6.4.2 Current Consumption in Other Modes

**Table 12: Current Consumption in Modem-sleep Mode**

Mode	CPU Frequency (MHz)	Description	Typ	
			All Peripherals Clocks Disabled (mA)	All Peripherals Clocks Enabled (mA) <sup>1</sup>
Modem-sleep <sup>2,3</sup>	80	CPU is running	12.1	13.0
		WFI (Wait-for-Interrupt)	9.4	10.3
	120	CPU is running	14.7	15.6
		WFI (Wait-for-Interrupt)	10.7	11.5

<sup>1</sup> In practice, the current consumption might be different depending on which peripherals are enabled.

<sup>2</sup> In Modem-sleep mode, Wi-Fi is clock gated.

<sup>3</sup> In Modem-sleep mode, the consumption might be higher when accessing flash. For a flash rated at 80 Mbit/s, in SPI 2-line mode the consumption is 10 mA.

**Table 13: Current Consumption in Low-Power Modes**

Work mode	Description	Typ	Unit
Light-sleep	—	140	μA
Deep-sleep	Only RTC timer is powered on	5	μA

Power off	CHIP_EN is set to low level, and the chip is powered off	1	$\mu\text{A}$
-----------	--	---	---------------

## 7 RF Characteristics

This section contains tables with RF characteristics of the Espressif product.

The RF data is measured at the antenna port, where RF cable is connected, including the front-end loss. The external antennas used for the tests on the modules with external antenna connectors have an impedance of 50  $\Omega$ . Devices should operate in the center frequency range allocated by regional regulatory authorities. The target center frequency range and the target transmit power are configurable by software. See [ESP RF Test Tool and Test Guide](#) for instructions.

Unless otherwise stated, the RF tests are conducted with a 3.3 V ( $\pm 5\%$ ) supply at 25 °C ambient temperature.

### 7.1 Wi-Fi Radio

#### 7.1.1 Wi-Fi RF Standards

**Table 14: Wi-Fi RF Standards**

Name	Description
Center frequency range of operating channel	2412 ~ 2484 MHz
Wi-Fi wireless standard	IEEE 802.11b/g/n
Data rate (20 MHz)	11b: 1, 2, 5.5 and 11 Mbps 11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 11n: MCS 0-7, 72.2 Mbps (Max)
Antenna type	PCB antenna

#### 7.1.2 Wi-Fi RF Transmitter (TX) Characteristics

Target TX power is configurable based on device or certification requirements. The default characteristics are provided in Table 15.

**Table 15: TX Power with Spectral Mask and EVM Meeting 802.11 Standards**

Rate	Min (dBm)	Typ (dBm)	Max (dBm)
802.11b, 1 Mbps	—	21	—
802.11b, 11 Mbps	—	21	—
802.11g, 6 Mbps	—	21	—
802.11g, 54 Mbps	—	19	—
802.11n, HT20, MCS 0	—	19	—
802.11n, HT20, MCS 7	—	18	—

Table 16: TX EVM Test

Rate	Min (dB)	Typ (dB)	SL <sup>1</sup> (dB)
802.11b, 1 Mbps, @21 dBm	—	-24	-10
802.11b, 11 Mbps, @21 dBm	—	-24	-10
802.11g, 6 Mbps, @21 dBm	—	-23	-5
802.11g, 54 Mbps, @19 dBm	—	-30	-25
802.11n, HT20, MCS 0, @20 dBm	—	-27	-5
802.11n, HT20, MCS 7, @18 dBm	—	-31	-27

<sup>1</sup> SL stands for standard limit value.

### 7.1.3 Wi-Fi RF Receiver (RX) Characteristics

Table 17: RX Sensitivity

Rate	Min (dBm)	Typ (dBm)	Max (dBm)
802.11b, 1 Mbps	—	-99.0	—
802.11b, 2 Mbps	—	-96.5	—
802.11b, 5.5 Mbps	—	-94.0	—
802.11b, 11 Mbps	—	-90.0	—
802.11g, 6 Mbps	—	-94.0	—
802.11g, 9 Mbps	—	-92.0	—
802.11g, 12 Mbps	—	-91.0	—
802.11g, 18 Mbps	—	-89.0	—
802.11g, 24 Mbps	—	-86.0	—
802.11g, 36 Mbps	—	-83.0	—
802.11g, 48 Mbps	—	-78.5	—
802.11g, 54 Mbps	—	-77.0	—
802.11n, HT20, MCS 0	—	-92.5	—
802.11n, HT20, MCS 1	—	-90.5	—
802.11n, HT20, MCS 2	—	-87.5	—
802.11n, HT20, MCS 3	—	-84.5	—
802.11n, HT20, MCS 4	—	-81.5	—
802.11n, HT20, MCS 5	—	-77.5	—
802.11n, HT20, MCS 6	—	-75.5	—
802.11n, HT20, MCS 7	—	-74.0	—

Table 18: Maximum RX Level

Rate	Min (dBm)	Typ (dBm)	Max (dBm)
802.11b, 1 Mbps	—	5	—

Cont'd on next page

Table 18 – cont'd from previous page

Rate	Min (dBm)	Typ (dBm)	Max (dBm)
802.11b, 11 Mbps	—	5	—
802.11g, 6 Mbps	—	5	—
802.11g, 54 Mbps	—	0	—
802.11n, HT20, MCS 0	—	5	—
802.11n, HT20, MCS 7	—	0	—

Table 19: RX Adjacent Channel Rejection

Rate	Min (dB)	Typ (dB)	Max (dB)
802.11b, 1 Mbps	—	35	—
802.11b, 11 Mbps	—	35	—
802.11g, 6 Mbps	—	31	—
802.11g, 54 Mbps	—	20	—
802.11n, HT20, MCS 0	—	16	—
802.11n, HT20, MCS 7	—	25	—

## 7.2 Bluetooth LE Radio

### 7.2.1 Bluetooth LE RF Transmitter (TX) Characteristics

Table 20: Transmitter General Characteristics

Parameter	Min	Typ	Max	Unit
RF transmit power	—	3	—	dBm
Gain control step	—	3	—	dB
RF power control range	-24	—	20	dBm

Table 21: Transmitter Characteristics - Bluetooth LE 1 Mbps

Parameter	Description	Min	Typ	Max	Unit
In-band emissions	$F = F_0 \pm 2 \text{ MHz}$	—	-32.0	—	dBm
	$F = F_0 \pm 3 \text{ MHz}$	—	-38.0	—	dBm
	$F = F_0 \pm > 3 \text{ MHz}$	—	-41.0	—	dBm
Modulation characteristics	$\Delta f_{1\text{avg}}$	—	249.0	—	kHz
	$\Delta f_{2\text{max}}$	—	246.0	—	kHz
	$\Delta f_{2\text{avg}}/\Delta f_{1\text{avg}}$	—	1.1	—	—
Carrier frequency offset	$\text{Max }  f_n _{n=0, 1, 2, \dots, k}$	—	2.0	—	kHz
Carrier frequency drift	$\text{Max }  f_0 - f_n _{n=2, 3, 4, \dots, k}$	—	1.0	—	kHz
	$\text{Max }  f_0 - f_1 $	—	0.5	—	kHz
	$\text{Max }  f_n - f_{n-5} _{n=6, 7, 8, \dots, k}$	—	1.0	—	kHz



Table 22: Transmitter Characteristics - Bluetooth LE 2 Mbps

Parameter	Description	Min	Typ	Max	Unit
In-band emissions	$F = F_0 \pm 4 \text{ MHz}$	—	-40.0	—	dBm
	$F = F_0 \pm 5 \text{ MHz}$	—	-43.0	—	dBm
	$F = F_0 \pm > 5 \text{ MHz}$	—	-44.0	—	dBm
Modulation characteristics	$\Delta f_{1\text{avg}}$	—	498.0	—	kHz
	$\Delta f_{2\text{max}}$	—	589.0	—	kHz
	$\Delta f_{2\text{avg}}/\Delta f_{1\text{avg}}$	—	1.2	—	—
Carrier frequency offset	$\text{Max }  f_n _{n=0, 1, 2, \dots, k}$	—	1.0	—	kHz
Carrier frequency drift	$\text{Max }  f_0 - f_n _{n=2, 3, 4, \dots, k}$	—	3.0	—	kHz
	$\text{Max }  f_0 - f_1 $	—	2.4	—	kHz
	$\text{Max }  f_n - f_{n-5} _{n=6, 7, 8, \dots, k}$	—	1.2	—	kHz

Table 23: Transmitter Characteristics - Bluetooth LE 125 kbps

Parameter	Description	Min	Typ	Max	Unit
In-band emissions	$F = F_0 \pm 2 \text{ MHz}$	—	-32.0	—	dBm
	$F = F_0 \pm 3 \text{ MHz}$	—	-38.0	—	dBm
	$F = F_0 \pm > 3 \text{ MHz}$	—	-41.0	—	dBm
Modulation characteristics	$\Delta f_{1\text{avg}}$	—	248.0	—	kHz
	$\Delta f_{1\text{max}}$	—	224.0	—	kHz
Carrier frequency offset	$\text{Max }  f_n _{n=0, 1, 2, \dots, k}$	—	0.5	—	kHz
Carrier frequency drift	$\text{Max }  f_0 - f_n _{n=1, 2, 3, \dots, k}$	—	0.7	—	kHz
	$\text{Max }  f_0 - f_3 $	—	0.2	—	kHz
	$\text{Max }  f_n - f_{n-3} _{n=7, 8, 9, \dots, k}$	—	0.7	—	kHz

Table 24: Transmitter Characteristics - Bluetooth LE 500 kbps

Parameter	Description	Min	Typ	Max	Unit
In-band emissions	$F = F_0 \pm 2 \text{ MHz}$	—	-32.0	—	dBm
	$F = F_0 \pm 3 \text{ MHz}$	—	-38.0	—	dBm
	$F = F_0 \pm > 3 \text{ MHz}$	—	-41.0	—	dBm
Modulation characteristics	$\Delta f_{2\text{avg}}$	—	273.0	—	kHz
	$\Delta f_{2\text{max}}$	—	243.0	—	kHz
Carrier frequency offset	$\text{Max }  f_n _{n=0, 1, 2, \dots, k}$	—	0.5	—	kHz
Carrier frequency drift	$\text{Max }  f_0 - f_n _{n=1, 2, 3, \dots, k}$	—	0.7	—	kHz
	$\text{Max }  f_0 - f_3 $	—	0.7	—	kHz
	$\text{Max }  f_n - f_{n-3} _{n=7, 8, 9, \dots, k}$	—	0.2	—	kHz

## 7.2.2 Bluetooth LE RF Receiver (RX) Characteristics

Table 25: Receiver Characteristics - Bluetooth LE 1 Mbps

Parameter	Description	Min	Typ	Max	Unit
Sensitivity @30.8% PER	—	—	-98	—	dBm
Maximum received signal @30.8% PER	—	—	8	—	dBm
Co-channel C/I	—	—	8	—	dB
Adjacent channel selectivity C/I	$F = F_0 + 1 \text{ MHz}$	—	-1	—	dB
	$F = F_0 - 1 \text{ MHz}$	—	-3	—	dB
	$F = F_0 + 2 \text{ MHz}$	—	-26	—	dB
	$F = F_0 - 2 \text{ MHz}$	—	-28	—	dB
	$F \geq F_0 + 3 \text{ MHz}^{(1)}$	—	—	—	dB
	$F \leq F_0 - 3 \text{ MHz}$	—	-31	—	dB
Image frequency	—	—	-33	—	dB
Adjacent channel to image frequency	$F = F_{image} + 1 \text{ MHz}$	—	-32	—	dB
	$F = F_{image} - 1 \text{ MHz}$	—	-34	—	dB
Out-of-band blocking performance	30 MHz ~ 2000 MHz	—	-23	—	dBm
	2003 MHz ~ 2399 MHz	—	-30	—	dBm
	2484 MHz ~ 2997 MHz	—	-10	—	dBm
	3000 MHz ~ 12.75 GHz	—	-17	—	dBm
Intermodulation	—	—	-31	—	dBm

<sup>1</sup> Refer to the value of adjacent channel to image frequency when  $F = F_{image} - 1 \text{ MHz}$ .

Table 26: Receiver Characteristics - Bluetooth LE 2 Mbps

Parameter	Description	Min	Typ	Max	Unit
Sensitivity @30.8% PER	—	—	-95	—	dBm
Maximum received signal @30.8% PER	—	—	8	—	dBm
Co-channel C/I	$F = F_0 \text{ MHz}$	—	9	—	dB
Adjacent channel selectivity C/I	$F = F_0 + 2 \text{ MHz}$	—	-11	—	dB
	$F = F_0 - 2 \text{ MHz}$	—	-7	—	dB
	$F = F_0 + 4 \text{ MHz}^{(1)}$	—	—	—	dB
	$F = F_0 - 4 \text{ MHz}$	—	-30	—	dB
	$F \geq F_0 + 6 \text{ MHz}$	—	-35	—	dB
	$F \leq F_0 - 6 \text{ MHz}$	—	-29	—	dB
Image frequency	—	—	-35	—	dB
Adjacent channel to image frequency	$F = F_{image} + 2 \text{ MHz}$	—	-35	—	dB
	$F = F_{image} - 2 \text{ MHz}^{(2)}$	—	—	—	dB
Out-of-band blocking performance	30 MHz ~ 2000 MHz	—	-30	—	dBm
	2003 MHz ~ 2399 MHz	—	-34	—	dBm
	2484 MHz ~ 2997 MHz	—	-19	—	dBm
	3000 MHz ~ 12.75 GHz	—	-28	—	dBm
Intermodulation	—	—	-33	—	dBm

<sup>1</sup> Refer to the value of Image frequency.

<sup>2</sup> Refer to the value of Adjacent channel selectivity C/I when  $F = F_0 + 2 \text{ MHz}$ .

Table 27: Receiver Characteristics - Bluetooth LE 125 kbps

Parameter	Description	Min	Typ	Max	Unit
Sensitivity @30.8% PER	—	—	-106	—	dBm
Maximum received signal @30.8% PER	—	—	8	—	dBm
Co-channel C/I	F = FO MHz	—	3	—	dB
Adjacent channel selectivity C/I	F = FO + 1 MHz	—	-7	—	dB
	F = FO - 1 MHz	—	-5	—	dB
	F = FO + 2 MHz	—	-35	—	dB
	F = FO - 2 MHz	—	-34	—	dB
	F ≥ FO + 3 MHz <sup>(1)</sup>	—	—	—	dB
	F ≤ FO - 3 MHz	—	-37	—	dB
Image frequency	—	—	-41	—	dB
Adjacent channel to image frequency	F = F <sub>image</sub> + 1 MHz	—	-43	—	dB
	F = F <sub>image</sub> - 1 MHz	—	-38	—	dB

<sup>1</sup> Refer to the value of Adjacent channel to image frequency when F = F<sub>image</sub> - 1 MHz.

Table 28: Receiver Characteristics - Bluetooth LE 500 kbps

Parameter	Description	Min	Typ	Max	Unit
Sensitivity @30.8% PER	—	—	-102	—	dBm
Maximum received signal @30.8% PER	—	—	8	—	dBm
Co-channel C/I	F = FO MHz	—	4	—	dB
Adjacent channel selectivity C/I	F = FO + 1 MHz	—	-6	—	dB
	F = FO - 1 MHz	—	-5	—	dB
	F = FO + 2 MHz	—	-29	—	dB
	F = FO - 2 MHz	—	-32	—	dB
	F ≥ FO + 3 MHz <sup>(1)</sup>	—	—	—	dB
	F ≤ FO - 3 MHz	—	-36	—	dB
Image frequency	—	—	-34	—	dB
Adjacent channel to image frequency	F = F <sub>image</sub> + 1 MHz	—	-37	—	dB
	F = F <sub>image</sub> - 1 MHz	—	-31	—	dB

<sup>1</sup> Refer to the value of Adjacent channel to image frequency when F = F<sub>image</sub> - 1 MHz.

# 8 Module Schematics

This is the reference design of the module.

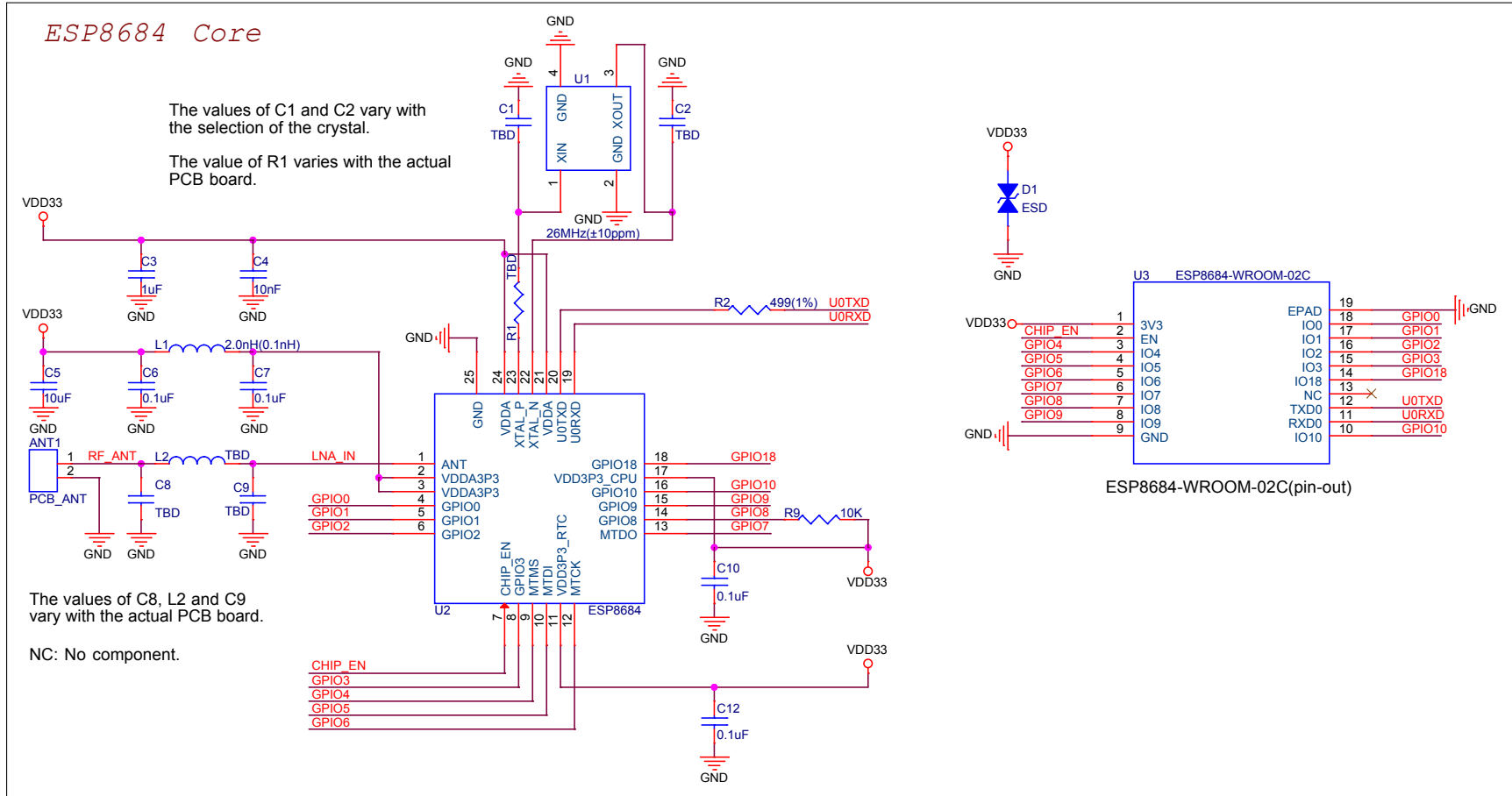


Figure 5: ESP8684-WROOM-02C Schematics

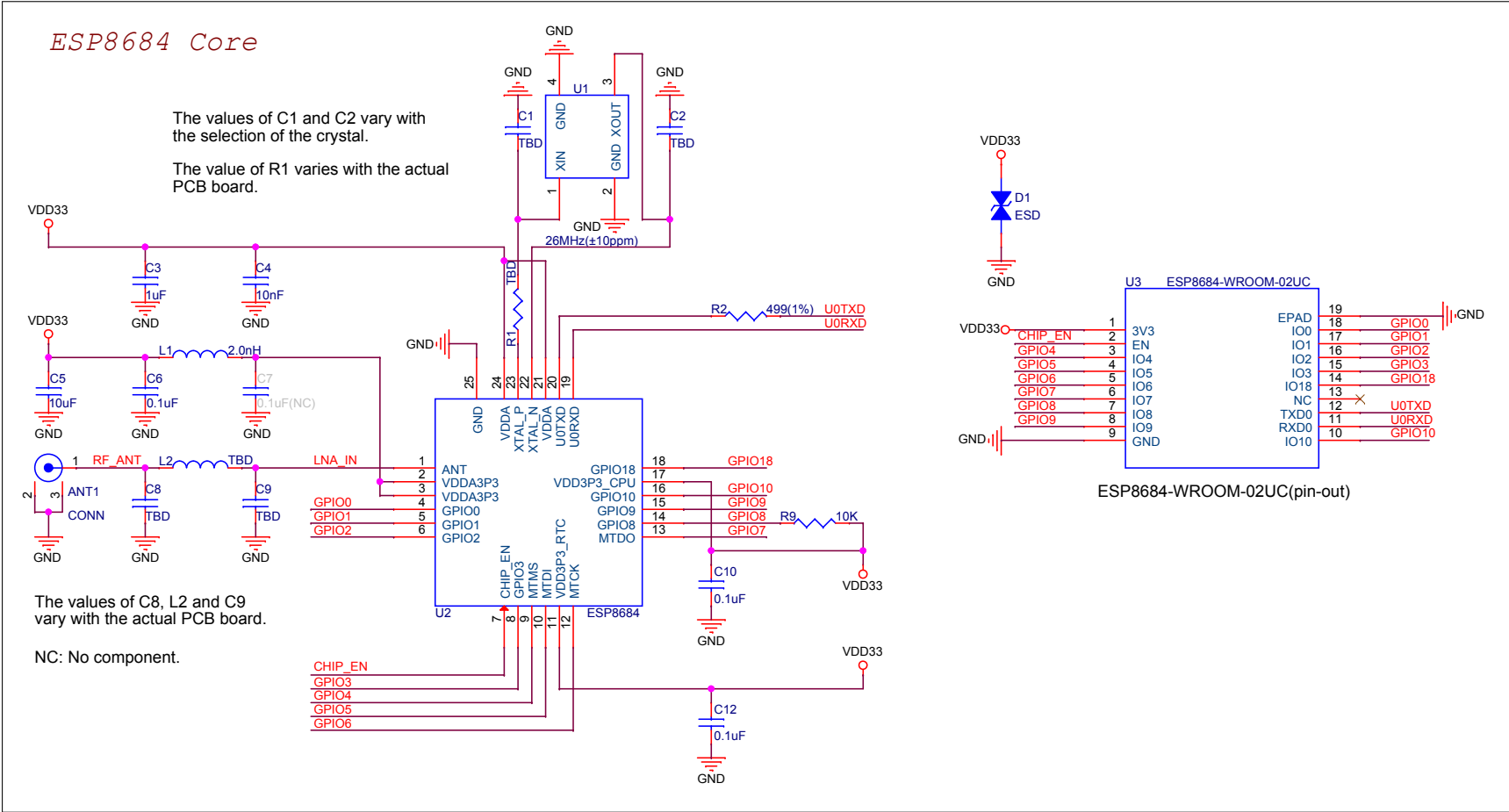


Figure 6: ESP8684-WROOM-02UC Schematics

## 9 Peripheral Schematics

This is the typical application circuit of the module connected with peripheral components (for example, power supply, antenna, reset button, JTAG interface, and UART interface).

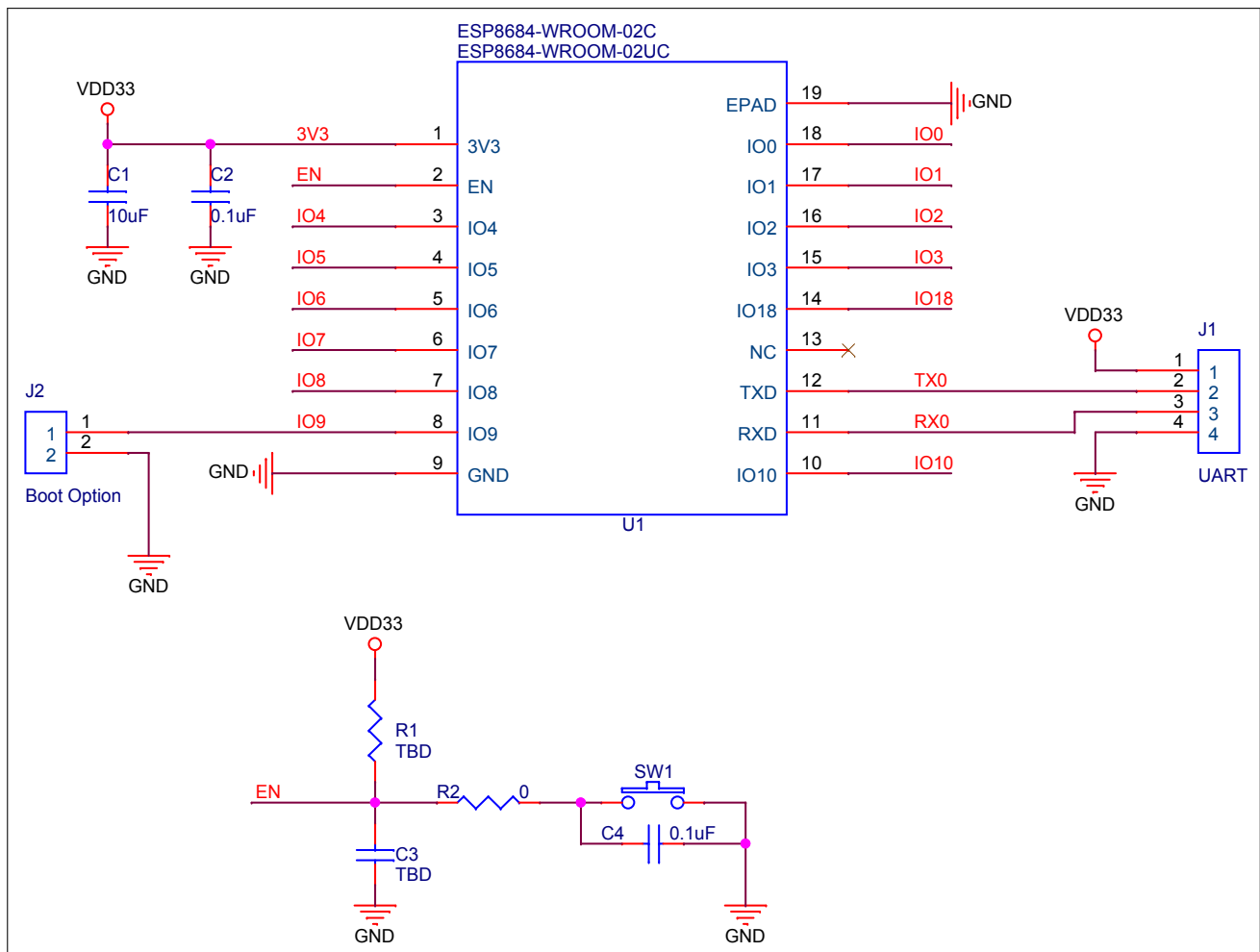


Figure 7: Peripheral Schematics

- Soldering the EPAD to the ground of the base board is not a must, however, it can optimize thermal performance. If you choose to solder it, please apply the correct amount of soldering paste. Too much soldering paste may increase the gap between the module and the baseboard. As a result, the adhesion between other pins and the baseboard may be poor.
- To ensure that the power supply to the ESP8684 chip is stable during power-up, it is advised to add an RC delay circuit at the EN pin. The recommended setting for the RC delay circuit is usually  $R = 10\text{ k}\Omega$  and  $C = 1\text{ }\mu\text{F}$ . However, specific parameters should be adjusted based on the power-up timing of the module and the power-up and reset sequence timing of the chip. For ESP8684's power-up and reset sequence timing diagram, please refer to Section *Power Scheme* in [ESP8684 Series Datasheet](#).
- UART0 is used to download firmware and log output. When using the AT firmware, please note that the UART GPIO is already configured (refer to [Hardware Connection](#)). It is recommended to use the default configuration.

# 10 Physical Dimensions

## 10.1 Module Dimensions

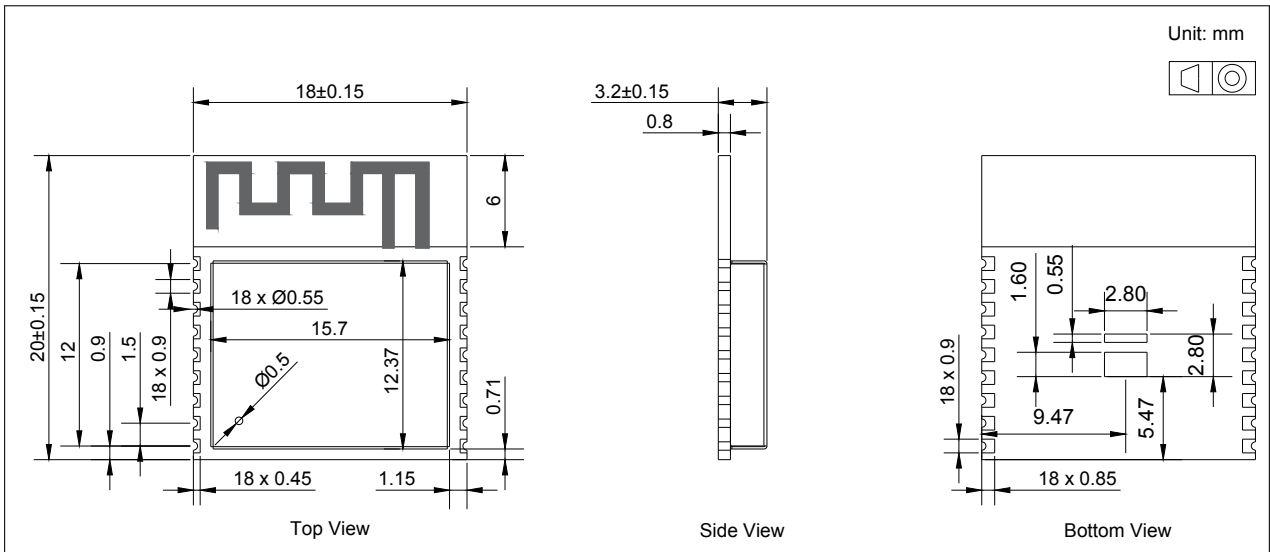


Figure 8: ESP8684-WROOM-02C Physical Dimensions

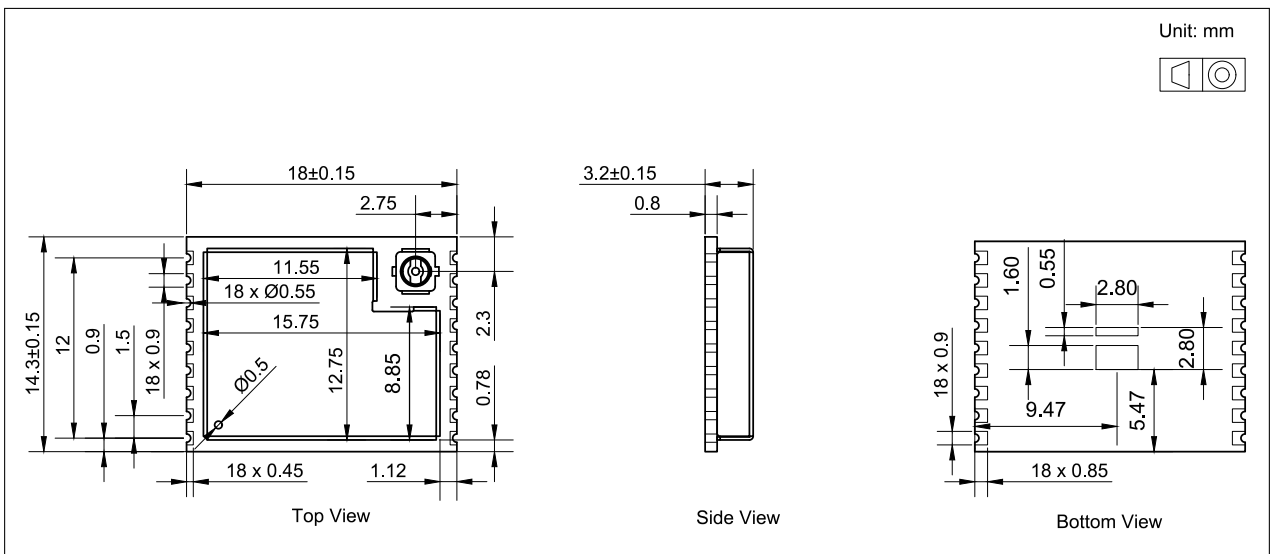


Figure 9: ESP8684-WROOM-02UC Physical Dimensions

**Note:**

For information about tape, reel, and product marking, please refer to [Espressif Module Packaging Information](#).

## 10.2 Dimensions of External Antenna Connector

ESP8684-WROOM-02UC uses the first generation external antenna connector as shown in Figure 10 *Dimensions of External Antenna Connector*. This connector is compatible with the following connectors:

- U.FL Series connector from Hirose
- MHF I connector from I-PEX
- AMC connector from Amphenol

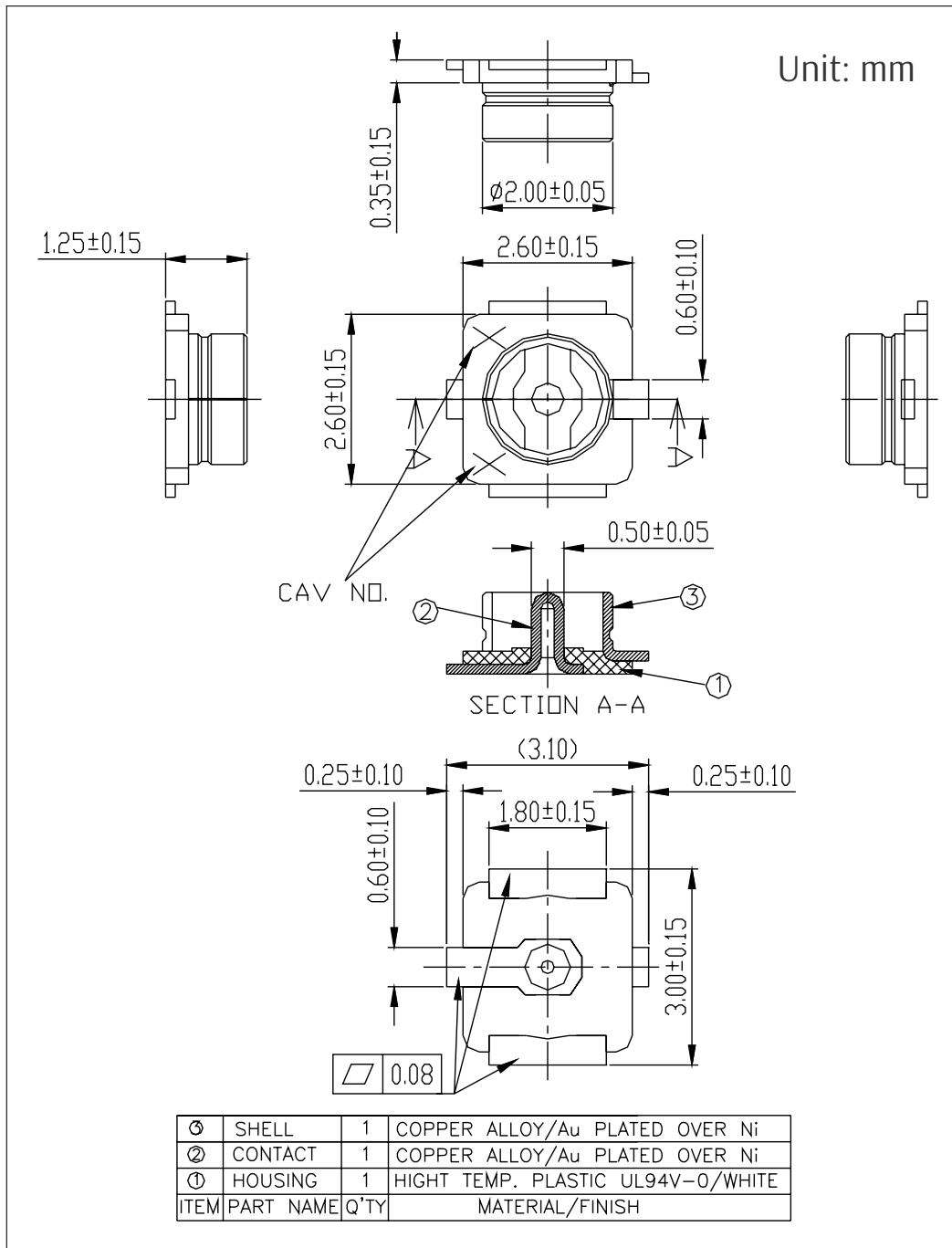


Figure 10: Dimensions of External Antenna Connector



# 11 PCB Layout Recommendations

## 11.1 PCB Land Pattern

This section provides the following resources for your reference:

- Figures for recommended PCB land patterns with all the dimensions needed for PCB design. See Figure 11 [ESP8684-WROOM-02C Recommended PCB Land Pattern](#) and Figure 12 [ESP8684-WROOM-02UC Recommended PCB Land Pattern](#).
- Source files of recommended PCB land patterns to measure dimensions not covered in Figure 11 and Figure 12. You can view the source files for [ESP8684-WROOM-02C](#) and [ESP8684-WROOM-02UC](#) with [Autodesk Viewer](#).
- 3D models of [ESP8684-WROOM-02C](#) and [ESP8684-WROOM-02UC](#). Please make sure that you download the 3D model file in .STEP format (beware that some browsers might add .txt).

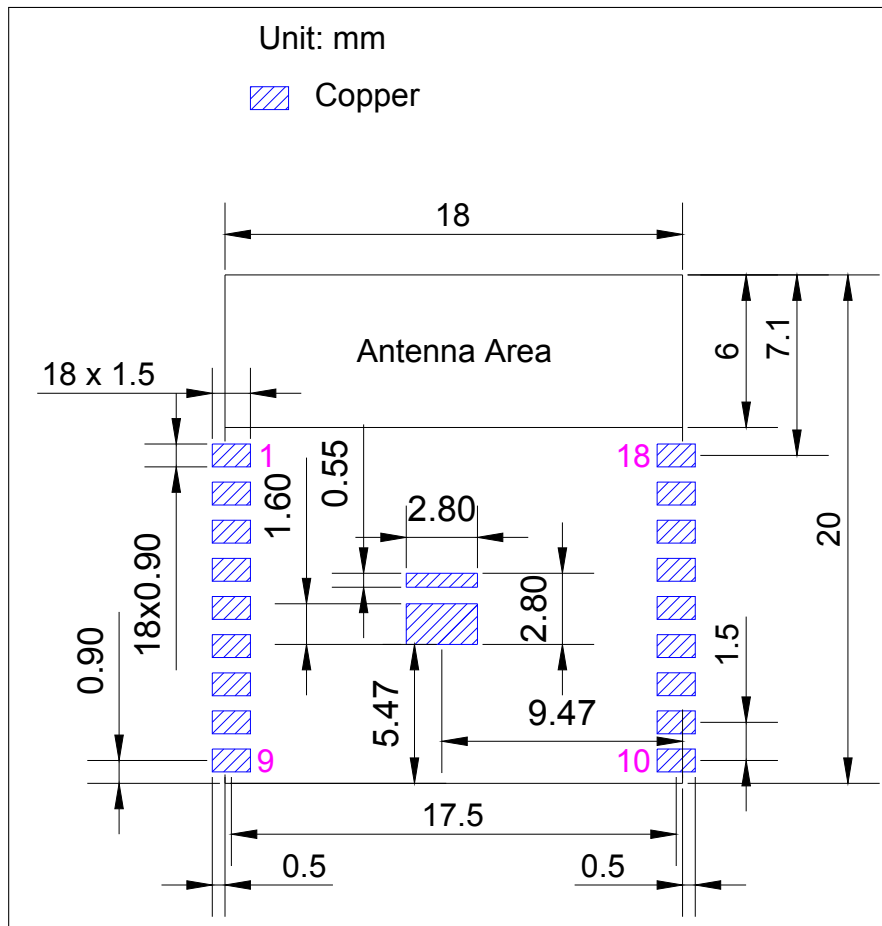


Figure 11: ESP8684-WROOM-02C Recommended PCB Land Pattern

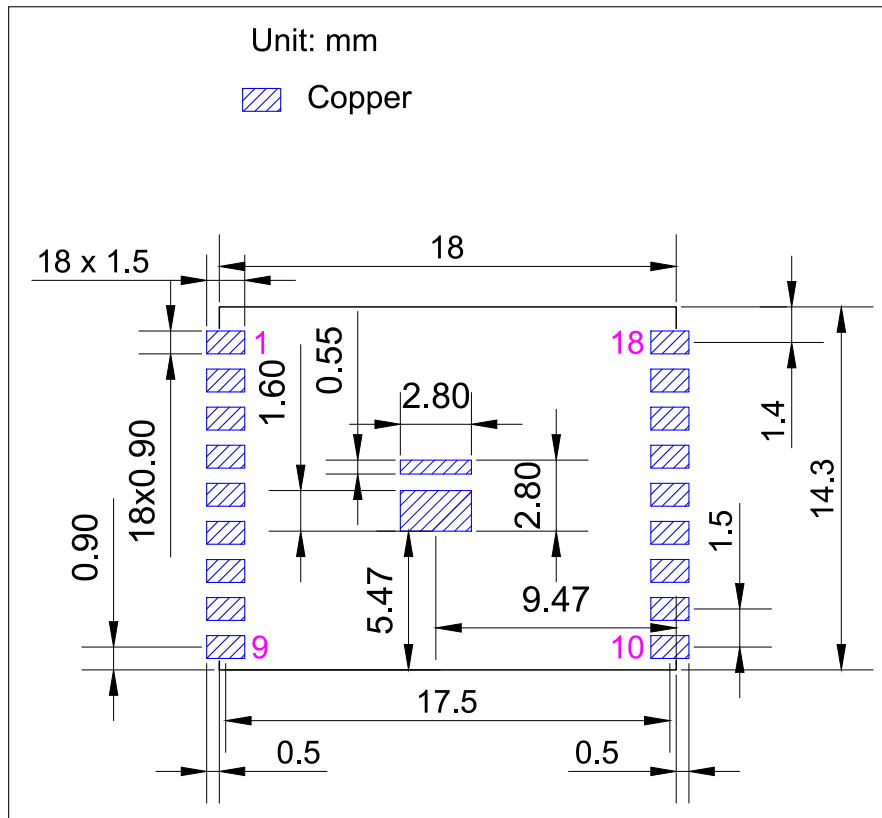


Figure 12: ESP8684-WROOM-02UC Recommended PCB Land Pattern

## 11.2 Module Placement for PCB Design

If module-on-board design is adopted, attention should be paid while positioning the module on the base board. The interference of the base board on the module's antenna performance should be minimized.

For details about module placement for PCB design, please refer to [ESP8684 Hardware Design Guidelines](#) > Section *Positioning a Module on a Base Board*.

## 12 Product Handling

### 12.1 Storage Conditions

The products sealed in moisture barrier bags (MBB) should be stored in a non-condensing atmospheric environment of  $< 40\text{ °C}$  and 90%RH. The module is rated at the moisture sensitivity level (MSL) of 3.

After unpacking, the module must be soldered within 168 hours with the factory conditions  $25\pm 5\text{ °C}$  and 60%RH. If the above conditions are not met, the module needs to be baked.

### 12.2 Electrostatic Discharge (ESD)

- Human body model (HBM):  $\pm 2000\text{ V}$
- Charged-device model (CDM):  $\pm 500\text{ V}$

### 12.3 Reflow Profile

Solder the module in a single reflow.

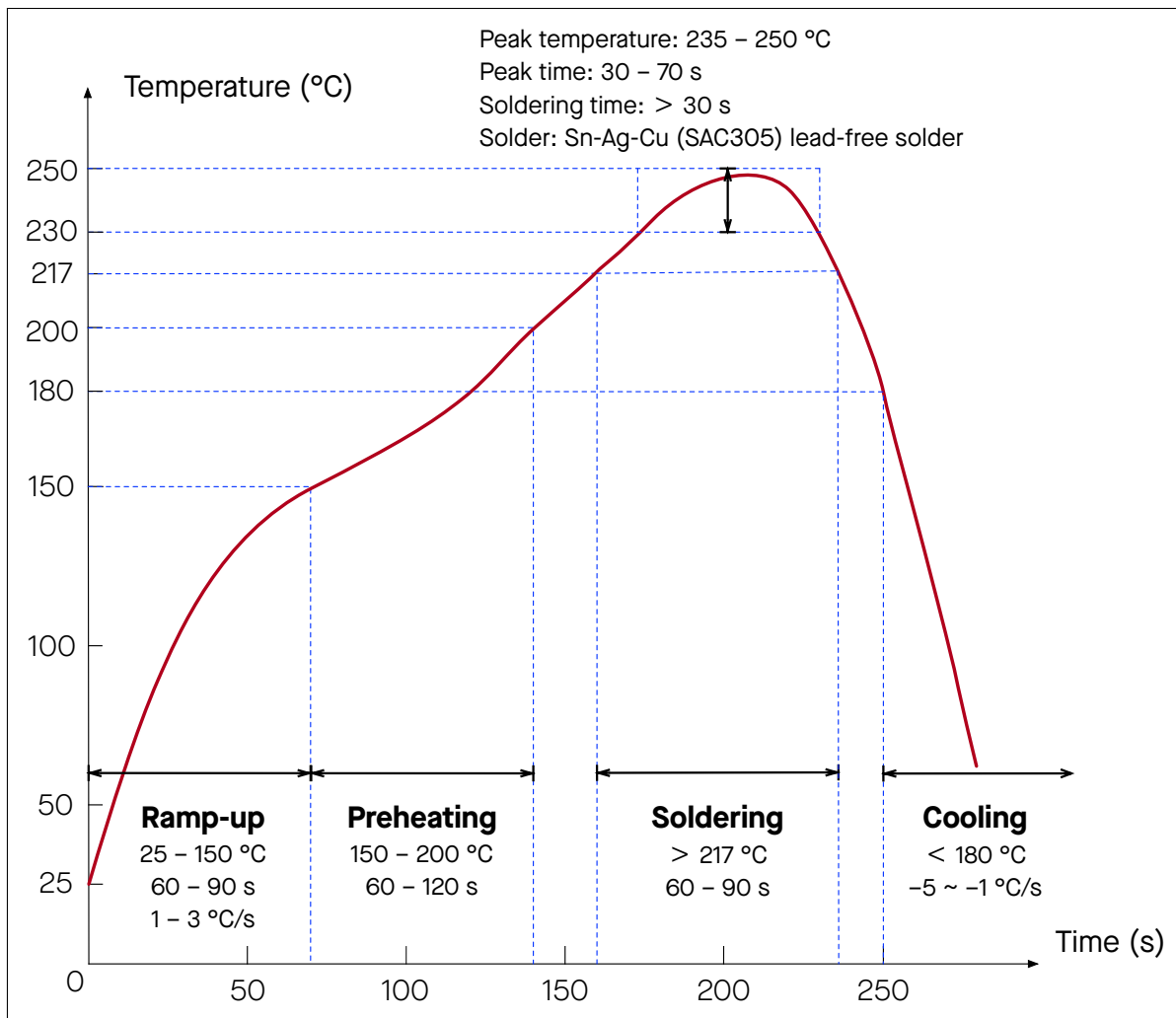


Figure 13: Reflow Profile

## 12.4 Ultrasonic Vibration

Avoid exposing Espressif modules to vibration from ultrasonic equipment, such as ultrasonic welders or ultrasonic cleaners. This vibration may induce resonance in the in-module crystal and lead to its malfunction or even failure. As a consequence, **the module may stop working or its performance may deteriorate.**

## Related Documentation and Resources

### Related Documentation

- [ESP8684 Series Datasheet](#) – Specifications of the ESP8684 hardware.
- [ESP8684 Technical Reference Manual](#) – Detailed information on how to use the ESP8684 memory and peripherals.
- [ESP8684 Hardware Design Guidelines](#) – Guidelines on how to integrate the ESP8684 into your hardware product.
- [ESP8684 Series SoC Errata](#) – Descriptions of known errors in ESP8684 series of SoCs.
- *Certificates*  
<https://espressif.com/en/support/documents/certificates>
- *ESP8684 Product/Process Change Notifications (PCN)*  
<https://espressif.com/en/support/documents/pcns?keys=ESP8684>
- *Documentation Updates and Update Notification Subscription*  
<https://espressif.com/en/support/download/documents>

### Developer Zone

- [ESP-IDF Programming Guide for ESP8684](#) – Extensive documentation for the ESP-IDF development framework.
- *ESP-IDF* and other development frameworks on GitHub.  
<https://github.com/espressif>
- *ESP32 BBS Forum* – Engineer-to-Engineer (E2E) Community for Espressif products where you can post questions, share knowledge, explore ideas, and help solve problems with fellow engineers.  
<https://esp32.com/>
- *The ESP Journal* – Best Practices, Articles, and Notes from Espressif folks.  
<https://blog.espressif.com/>
- See the tabs *SDKs and Demos, Apps, Tools, AT Firmware*.  
<https://espressif.com/en/support/download/sdks-demos>

### Products

- *ESP8684 Series SoCs* – Browse through all ESP8684 SoCs.  
<https://espressif.com/en/products/socs?id=ESP8684>
- *ESP8684 Series Modules* – Browse through all ESP8684-based modules.  
<https://espressif.com/en/products/modules?id=ESP8684>
- *ESP8684 Series DevKits* – Browse through all ESP8684-based devkits.  
<https://espressif.com/en/products/devkits?id=ESP8684>
- *ESP Product Selector* – Find an Espressif hardware product suitable for your needs by comparing or applying filters.  
<https://products.espressif.com/#/product-selector?language=en>

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- See the tabs *Sales Questions, Technical Enquiries, Circuit Schematic & PCB Design Review, Get Samples* (Online stores), *Become Our Supplier, Comments & Suggestions*.  
<https://espressif.com/en/contact-us/sales-questions>

## Revision History

Date	Version	Release notes
2025-03-14	v1.3	Updated Table 15 <i>Wi-Fi RF Transmitter (TX) Characteristics</i> and Table 16 <i>Wi-Fi RF Transmitter (TX) Characteristics</i>
2025-01-20	v1.2	<ul style="list-style-type: none"> <li>Table 1 <i>Series Comparison</i> and table 2 <i>Series Comparison</i>:               <ul style="list-style-type: none"> <li>Update Ordering Code from ESP8684-WROOM-02C-H2 to ESP8684-WROOM-02C-H2X</li> <li>Update Ordering Code from ESP8684-WROOM-02C-H4 to ESP8684-WROOM-02C-H4X</li> <li>Update Ordering Code from ESP8684-WROOM-02UC-H2 to ESP8684-WROOM-02UC-H2X</li> <li>Update Ordering Code from ESP8684-WROOM-02UC-H4 to ESP8684-WROOM-02UC-H4X</li> </ul> </li> </ul>
2024-12-23	v1.1	<ul style="list-style-type: none"> <li>In Chapter 1 <i>Module Overview</i>, renamed 1.2 <i>Description</i> to 1.2 <i>Series Comparison</i></li> <li>In Chapter 3.1 <i>Pin Layout</i>, Add annotations to the antenna keepout zone</li> <li>Improved the structure, formatting, and wording in:               <ul style="list-style-type: none"> <li>Chapter 4 <i>Boot Configurations</i> (use to be Section 3.3 <i>Strapping Pins</i>)</li> <li>Chapter 6 <i>Electrical Characteristics</i> and 7 <i>RF Characteristics</i> (used to be Chapter 4 <i>Electrical Characteristics</i>)</li> <li>Chapter 10.1 <i>Module Dimensions</i> and 11 <i>PCB Layout Recommendations</i> (used to be Chapter 7 <i>Physical Dimensions and PCB Land Pattern</i>)</li> </ul> </li> <li>Added Chapter 5 <i>Peripherals</i></li> <li>Added Chapter 11.2 <i>Module Placement for PCB Design</i></li> </ul>
2024-08-16	v1.0	<p>Updated the following module variants, upgrading the maximum operating ambient temperature to 105°C:</p> <ul style="list-style-type: none"> <li>Removed ESP8684-WROOM-02C-N2, ESP8684-WROOM-02C-N4, ESP8684-WROOM-02UC-N2 and ESP8684-WROOM-02UC-N4</li> <li>Added ESP8684-WROOM-02C-H2, ESP8684-WROOM-02C-H4, ESP8684-WROOM-02UC-H2 and ESP8684-WROOM-02UC-H4</li> </ul>
2024-01-09	v0.7	Added an item about Bluetooth 5.3 certification in Section 1.1 <i>Features</i> .
2023-02-21	v0.6	<ul style="list-style-type: none"> <li>Added information of ESP8684-WROOM-02UC</li> <li>Added a note to table 3 <i>Pin Description</i></li> </ul>
2022-08-29	v0.5	Preliminary release



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